# Nch 100V 20A Power MOSFET

V <sub>DSS</sub>	100V
R <sub>DS(on)</sub> (Max.)	46mΩ
I <sub>D</sub>	±20A
P <sub>D</sub>	20W

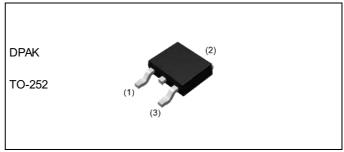
# Features

- 1) Low on resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free lead plating; RoHS compliant

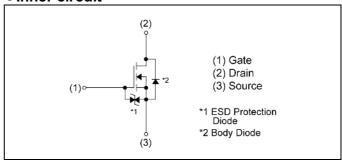
# Application

Switching

#### Outline



# Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
	Tape width (mm)	16
Type	Quantity (pcs)	2500
	Taning and	TL
	Taping code	TL1
	Marking	RD3P200SN

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	100	V
Continuous drain current	I <sub>D</sub> *1	±20	А
Pulsed drain current	I <sub>DP</sub> *2	±80	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *3	10	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	72	mJ
Power dissipation	P <sub>D</sub> *4	20	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

# ●Thermal resistance

Parameter	Symbol	Values			Lloit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *4	-	1	6.25	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Downston	Correcte ed	Conditions	Values			l lait	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	100	-	-	V	
Breakdown voltage temperature coefficient $\frac{\Delta V_{(BR)DSS}}{\Delta T_j} I_D = 1 \text{mA}$		I <sub>D</sub> = 1mA referenced to 25°C	-	116.9	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±10	μA	
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient $\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$		I <sub>D</sub> = 1mA referenced to 25°C	-	-3.6	-	mV/°C	
Static drain - source	D *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	33	46	0	
on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = 4.0V, I <sub>D</sub> = 20A	- 36		50	mΩ	
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	4.9	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = 10V, I <sub>D</sub> = 20A	15	-	-	S	

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumbal	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Orlit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	2100	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	1	180	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	1	120	1		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 50V, V_{GS} = 10V$	1	100	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 10A	ı	35	1	no	
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 5\Omega$	1	150	-	ns	
Fall time	t <sub>f</sub> *5	$R_G = 10\Omega$	-	100	-		

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Daramatar	Symbol Conditions		Values			I India
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≃ 50V,	-	55	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 20A,	-	5.5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	12.5	-	

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Doromotor	Symbol Conditions		Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub> *1	T <sub>a</sub> = 25°C	1	1	14	Α
Pulse forward current	I <sub>SP</sub> *2	1 <sub>a</sub> = 25 C	-	-	80	Α
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 10A, V <sub>GS</sub> =0V	-	53	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/µs	- 1	120	- 1	μC

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw≦10µs , Duty cycle≦1%

<sup>\*3</sup> L  $\simeq$  1mH, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> T<sub>c</sub>=25°C

<sup>\*5</sup> Pulsed

Fig.1 Power Dissipation Derating Curve

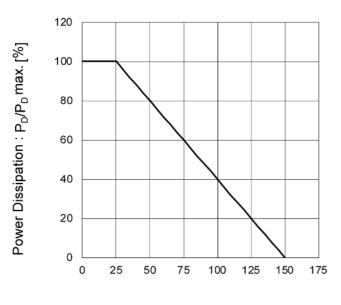
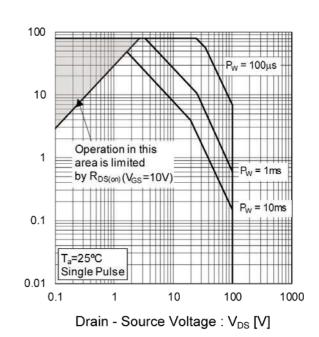


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Junction Temperature : T<sub>i</sub> [°C]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

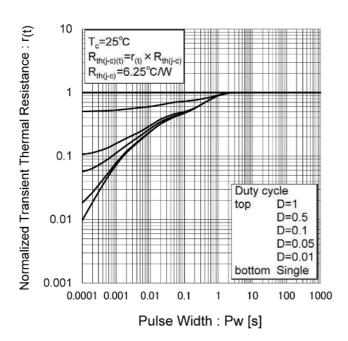


Fig.4 Single Pulse Maximum Power dissipation

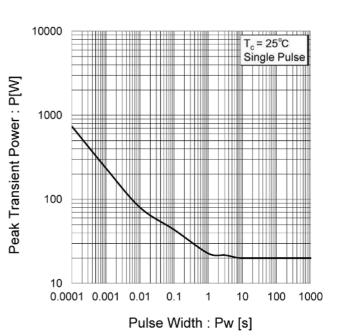


Fig.5 Typical Output Characteristics(I)

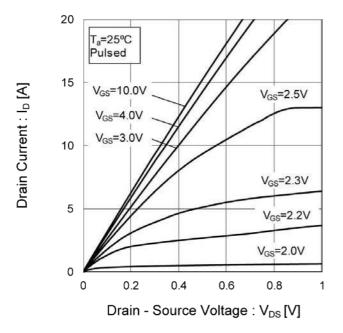
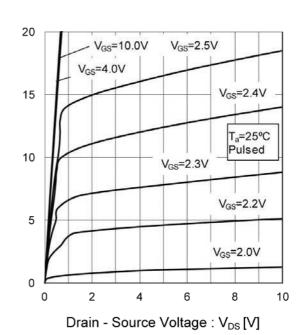


Fig.6 Typical Output Characteristics(II)



Drain Current: Ip [A]

Fig.7 Breakdown Voltage vs.
Junction Temperature

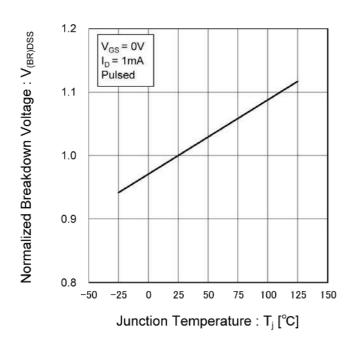


Fig.8 Typical Transfer Characteristics

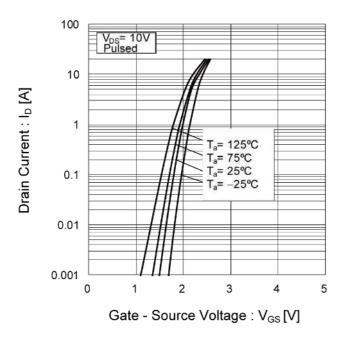


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

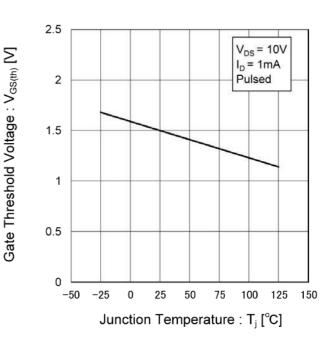
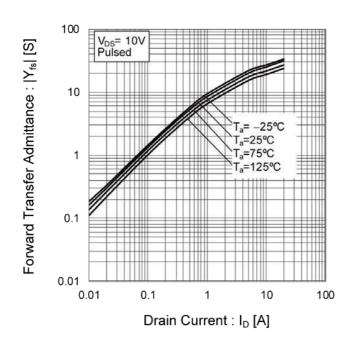


Fig.10 Forward Transfer Admittance vs.
Drain Current



6/12

Fig.11 Drain Current Derating Curve

120 100 **Drain Current Dissipation** 80 : I<sub>D</sub>/I<sub>D</sub>max. [%] 60 40 20 0 -25 0 25 50 75 100 125 150 Junction Temperature : T<sub>j</sub> [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

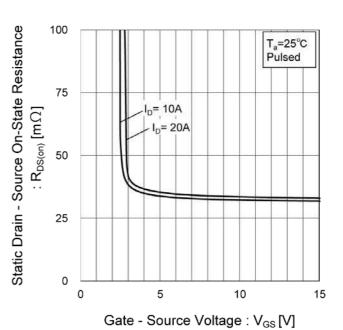


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

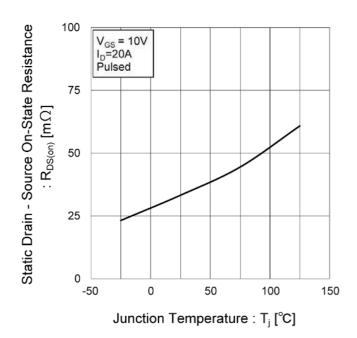


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

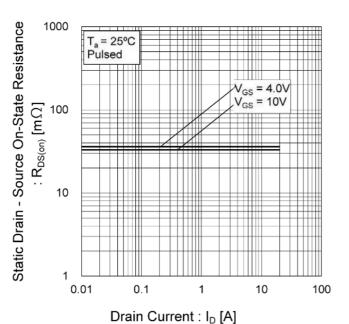


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

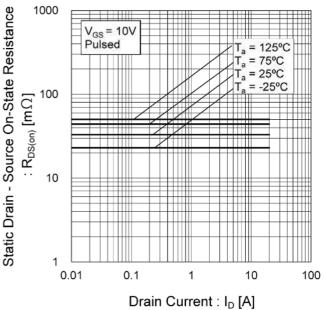


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

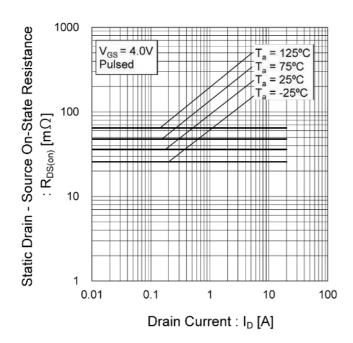


Fig.17 Typical Capacitance vs.

Drain - Source Voltage

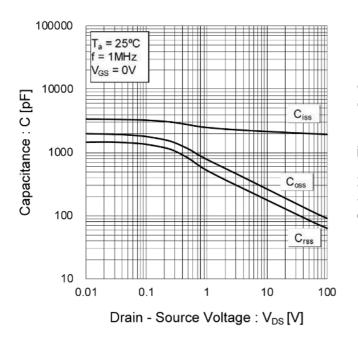


Fig.18 Switching Characteristics

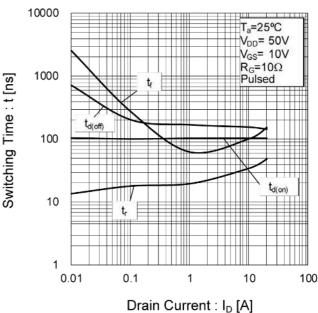


Fig.19 Dynamic Input Characteristics

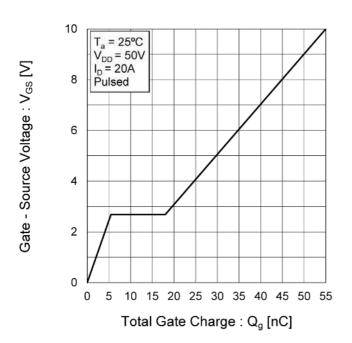
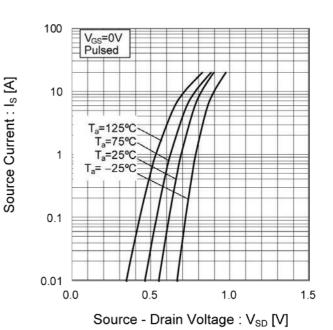


Fig.20 Source Current vs.

Source Drain Voltage



## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

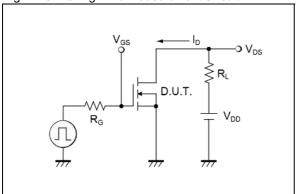


Fig.2-1 Gate Charge Measurement Circuit

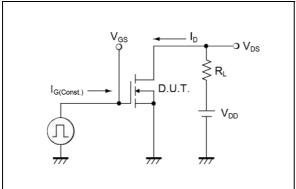


Fig.3-1 Avalanche Measurement Circuit

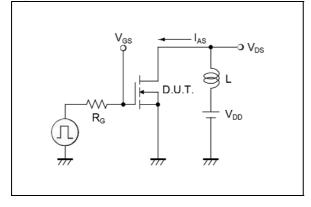


Fig.1-2 Switching Waveforms

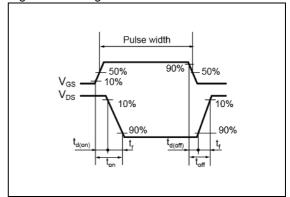


Fig.2-2 Gate Charge Waveform

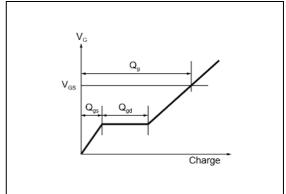
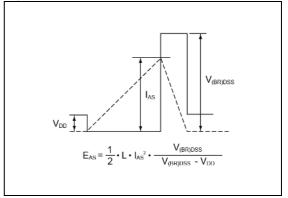
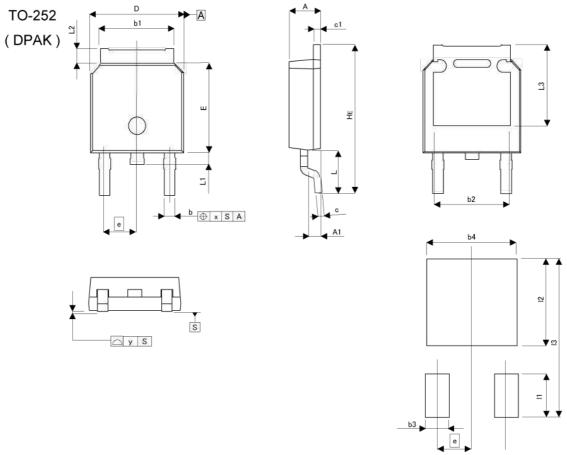


Fig.3-2 Avalanche Waveform



# ullet Dimensions (TL)



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

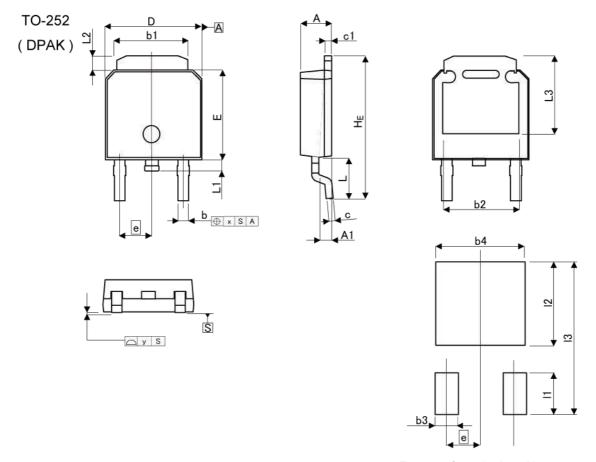
DIM -	MILIME	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.	10	0.2	201
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.091	
E	6.00	6.40	0.236	0.252
HE	9.50	10.50	0.374	0.413
L	2.	90	0.114	
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.30		0.2	209
X	-	0.10	-	0.004
У	-	0.10		0.004

DIM	MILIM	MILIMETERS		HES
	MIN	MAX	MIN	MAX
b3	₽	1.10	028	0.043
b4		5.40	S <del>=</del> s	0.213
11	<u>#</u>	2.90	WZX	0.114
12	*	5.50	5.71	0.217
13	25	10.50	WES	0.413

Dimension in mm/inches



# ● Dimensions (TL1)



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	ETERS	INCHES	
ואוט	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	4.	80	0.1	89
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.30		0.0	91
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	90	0.114	
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.209	
х	*	0.25	(E) (E)	0.010
у	₩.	0.10	0 <b>7</b> %	0.004
DIM I	MILIME	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b3	8	1.15	9 <b>4</b> 5	0.045
b4	I	5.55	6 <del>2</del> 3	0.219
11	E .	2.77	S (19)	0.109
12	-	5.50	(5)	0.217
13	2	10.40	2 VES	0.409

Dimension in mm/inches



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CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
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  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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